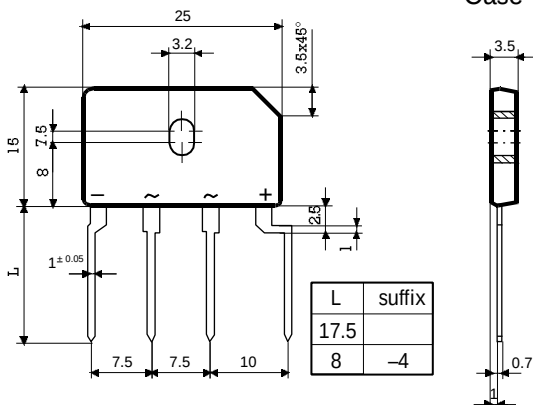


15 Amp. Glass Passivated Bridge Rectifier

Dimensions in mm.  Plastic Case <table border="1"> <thead> <tr> <th>L</th> <th>suffix</th> </tr> </thead> <tbody> <tr> <td>17.5</td> <td></td> </tr> <tr> <td>8</td> <td>-4</td> </tr> </tbody> </table> • Mounting Instructions • High temperature soldering guaranteed: 260 °C – 10 sc. • Recommended mounting torque: 8 Kg.cm.	L	suffix	17.5		8	-4	Voltage 50 to 1000 V. Current 15 A.  • Glass Passivated Junction Chips. • UL recognized under component index file number E130180. • Lead and polarity identifications. • Case: Molded Plastic. • Ideal for printed circuit board (P.C.B.). • High surge current capability. • The plastic material carries U/L recognition 94 V-O.
L	suffix						
17.5							
8	-4						

Maximum Ratings, according to IEC publication No. 134

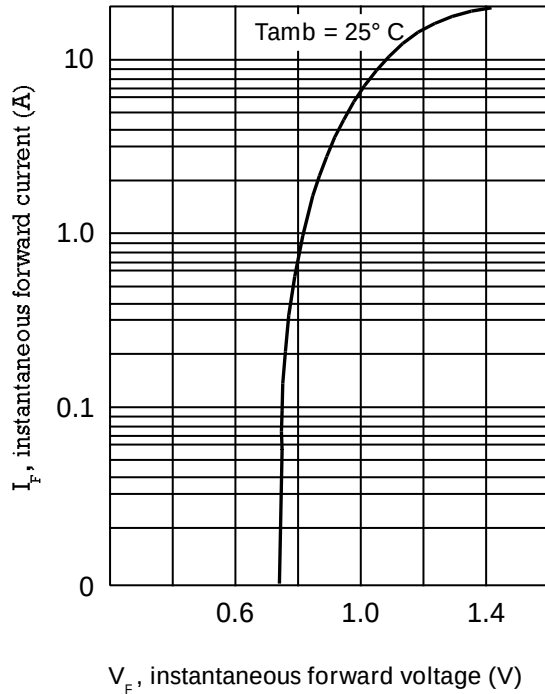
		FBI15A 1M1	FBI15B 1M1	FBI15D 1M1	FBI15G 1M1	FBI15J 1M1	FBI15K 1M1	FBI15M 1M1
V_{RRM}	Peak recurrent reverse voltage (V)	50	100	200	400	600	800	1000
V_{RMS}	Maximum RMS voltage (V)	35	70	140	280	420	560	700
$I_{F(AV)}$	Max. Average forward current with heatsink without heatsink	15.0 A at 75 °C 3.2 A at 25 °C						
I_{FSM}	10 ms. peak forward surge current (Jedec Method)	200 A						
I^2t	Current squared time (rating for fusing) (1ms.<t<10ms. Tc = 25°C)	110 A ² sec						
V_{DIS}	Dielectric strength (terminals to case, AC 1 min.)	2500 V						
T_j	Operating temperature range	– 55 to + 150 °C						
T_{stg}	Storage temperature range	– 55 to +150 °C						

Electrical Characteristics at Tamb = 25°C

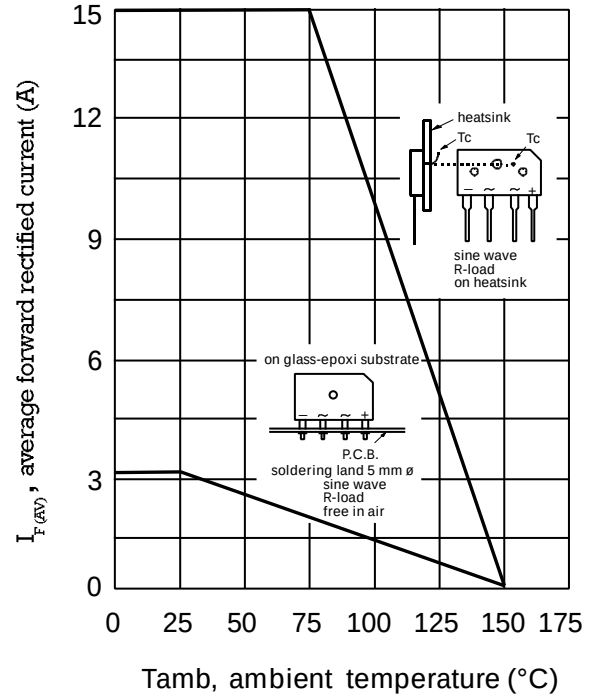
V_F	Max. forward voltage drop per diode at $I_F = 7.5$ A	1.10V
I_R	Max. instantaneous reverse current at V_{RRM}	5μA
$R_{th(j-c)}$	MAXIMUM THERMAL RESISTANCE Junction-Case. With Heatsink.	2.2 °C/W
$R_{th(j-a)}$	Junction-Ambient. Without Heatsink.	22 °C/W

Characteristic Curves

TYPICAL FORWARD CHARACTERISTIC



FORWARD CURRENT DERATING CURVE


MAXIMUM NON-REPETITIVE PEAK
FORWARD SURGE CURRENT
